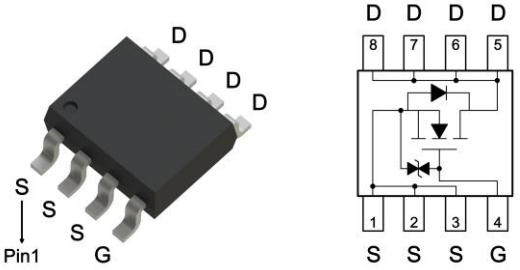
Product Summary

BV_{DSS}	100	V
$R_{DS(ON)}$ typ. @ V_{GS}=10V, I_D=10A	58	mΩ
$R_{DS(ON)}$ typ. @ V_{GS}=4.5V, I_D=8A	73	
I_D @ V_{GS}=10V, T_C=25°C	8	A
I_D @ V_{GS}=10V, T_A=25°C	3.7	

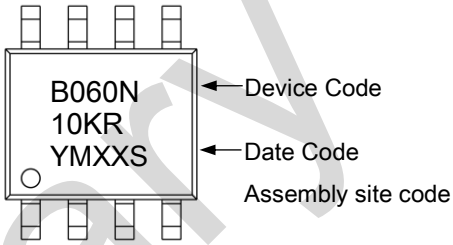
Features

- Low Gate Charge
- Fast Switching Characteristic
- Pb-free lead plating and halogen-free
- ESD protected gate

SOP-8



Marking



YMXXS: Date Code & Assembly site code Marking
Y: Year Code, the last digit of Christian year
M: Month Code

A: Jan	B: Feb	C: Mar	D: Apr	E: May	F: Jun
G: Jul	H: Aug	J: Sep	K: Oct	L: Nov	M: Dec

XX: Production Serial Number, 01~99
S: Assembly site code, Site 1: Blank, Site 2: G

Ordering Information

Device	Package	Shipping
MTB060N10KRQ8-0-TF-G	SOP-8	4000pcs / Tape & Reel

0: Product rank, zero for no rank products.
TF: Packing spec, TF: 4000pcs / tape & reel,13" reel.
G: Environment friendly grade: S for RoHS compliant products, G for RoHS compliant and green compound products.

Preliminary

Absolute Maximum Ratings (T_A=25°C)

Parameter			Symbol	Value	Unit
Drain-Source Voltage			V_{DS}	100	V
Gate-Source Voltage			V_{GS}	±20	
Continuous Drain Current @ V_{GS}=10V, T_C=25°C		*a	I_D	8	A
Continuous Drain Current @ V_{GS}=10V, T_C=100°C		*a		5.1	
Continuous Drain Current @ V_{GS}=10V, T_A=25°C		*b		3.7	
Continuous Drain Current @ V_{GS}=10V, T_A=70°C		*b		3	
Pulsed Drain Current		*c	I_{DM}	28	
Continuous Body Diode Forward Current @ T_C=25°C		*a	I_S	8	
Pulsed Body Diode Forward Current @ T_C=25°C		*a	I_{SM}	28	
Total Power Dissipation	T_C=25°C	*a	P_D	10	W
	T_C=100°C	*a		4	
	T_A=25°C	*b		2	
	T_A=70°C	*b		1.3	
Operating Junction and Storage Temperature Range			T_J, T_{stg}	-55~+150	°C
Steady State Thermal Resistance, Junction-to-Case			$R_{\theta JC}$	13	°C/W
Steady State Thermal Resistance, Junction-to-Ambient		*b	$R_{\theta JA}$	61	

Electrical Characteristics (T_A=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	100	-	-	V	V_{GS}=0V, I_D=250μA
$V_{GS(th)}$	1	-	2.5		V_{DS}=V_{GS}, I_D=250μA
G_{FS}	-	4	-	S	V_{DS}=10V, I_D=2A
I_{GSS}	-	-	±10	μA	V_{GS}=±16V, V_{DS}=0V
I_{DSS}	-	-	1		V_{DS}=80V, V_{GS}=0V
$R_{DS(ON)}$	-	58	76	mΩ	V_{GS}=10V, I_D=2A
	-	73	102		V_{GS}=4.5V, I_D=1A
Dynamic					
C_{iss}	-	317	-	pF	V_{DS}=50V, V_{GS}=0V, f=1MHz
C_{oss}	-	40	-		
C_{rss}	-	19	-		
R_g	-	6.6	-	Ω	f=1MHz
Q_g *d,e	-	3.7	-	nC	V_{DS}=50V, I_D=2A, V_{GS}=4.5V
Q_g *d,e	-	7.1	-		V_{DS}=50V, I_D=2A, V_{GS}=10V
Q_{gs} *d,e	-	1.1	-		
Q_{gd} *d,e	-	1.6	-		
$t_{d(ON)}$ *d,e	-	5.2	-	ns	V_{DS}=50V, I_D=2A, V_{GS}=10V, R_{GS}=1Ω
tr *d,e	-	17	-		
$t_{d(OFF)}$ *d,e	-	20	-		
t_f *d,e	-	7.3	-		
Source-Drain Diode					
V_{SD} *d	-	0.82	1.2	V	I_S=2A, V_{GS}=0V
t_{rr}	-	20	-	ns	I_F=2A, di/dt=100A/μs
Q_{rr}	-	12	-	nC	

Note:

*a. The power dissipation P_D is based on $T_{J(MAX)}$=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper Dissipation.

*b. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz copper, in a still air environment with T_A=25°C. The power dissipation P_D is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

*c. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.

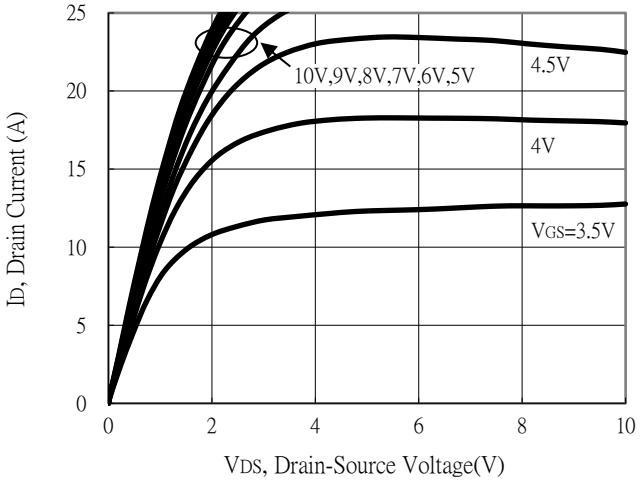
*d. Pulse Test : Pulse Width≤300μs, Duty Cycle≤2%.

*e. Independent of operating temperature.

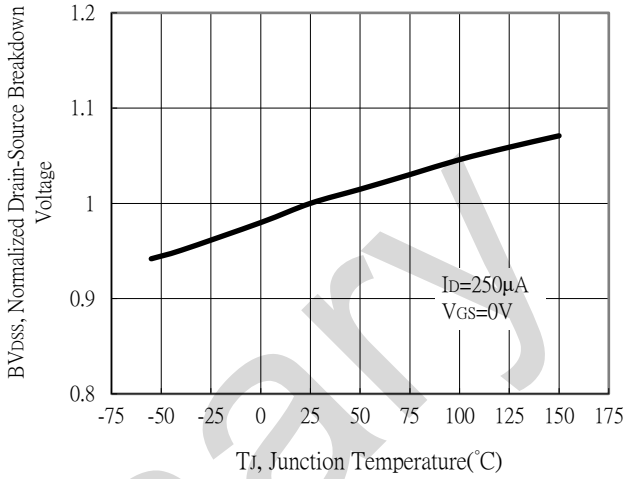
Preliminary

Typical Characteristics

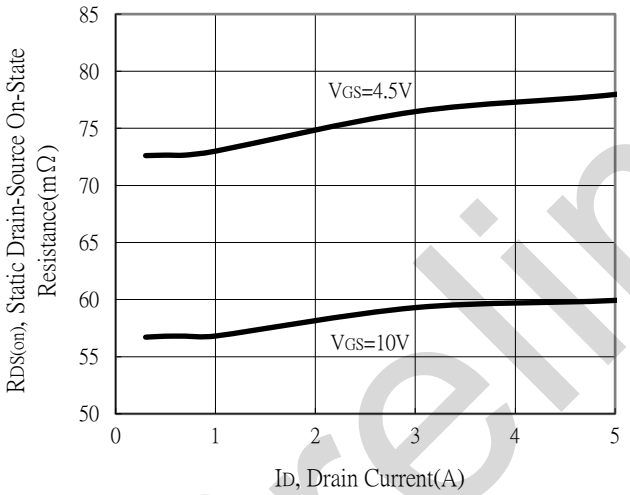
Typical Output Characteristics



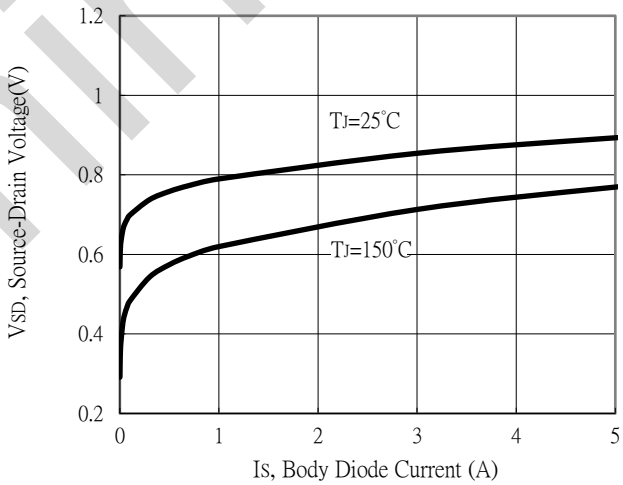
Breakdown Voltage vs Ambient Temperature



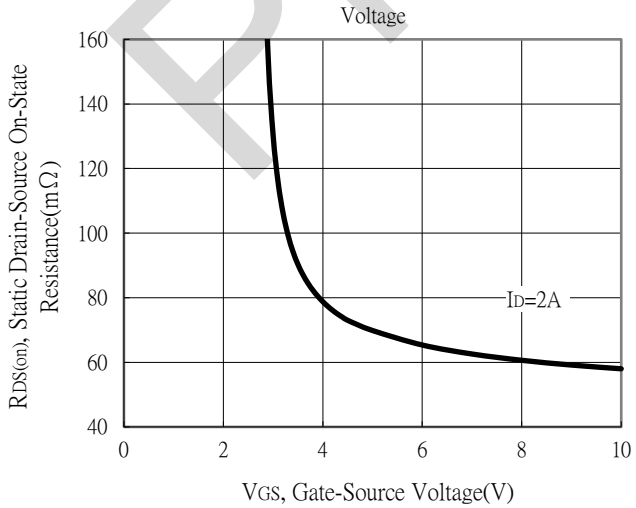
Static Drain-Source On-State resistance vs Drain Current



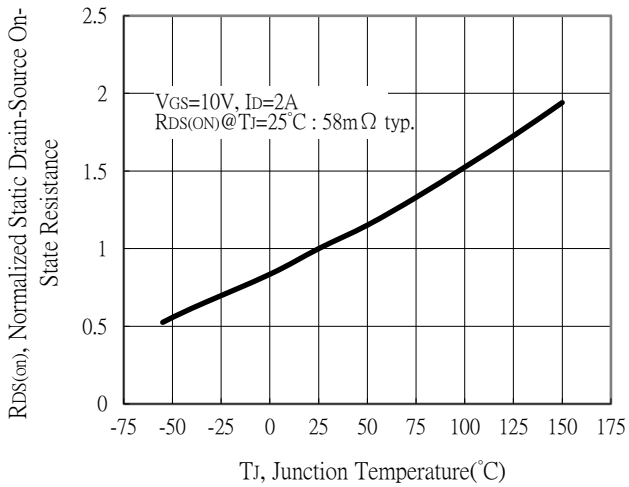
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage



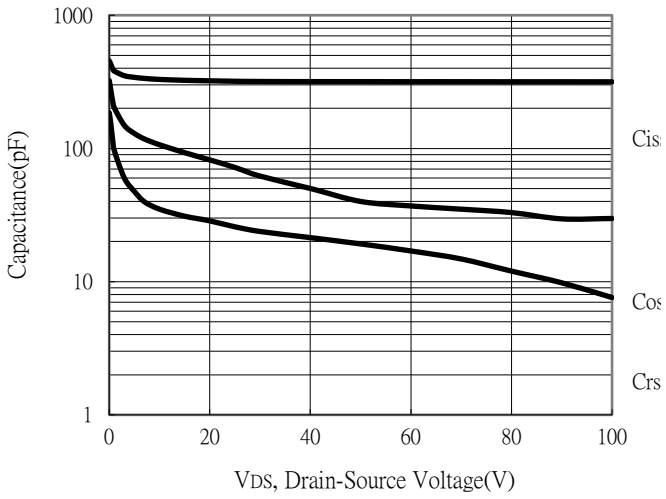
Drain-Source On-State Resistance vs Junction Temperature



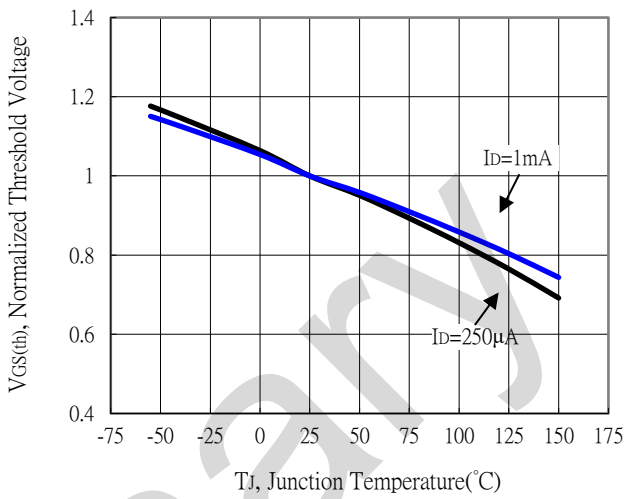
Preliminary

Typical Characteristics

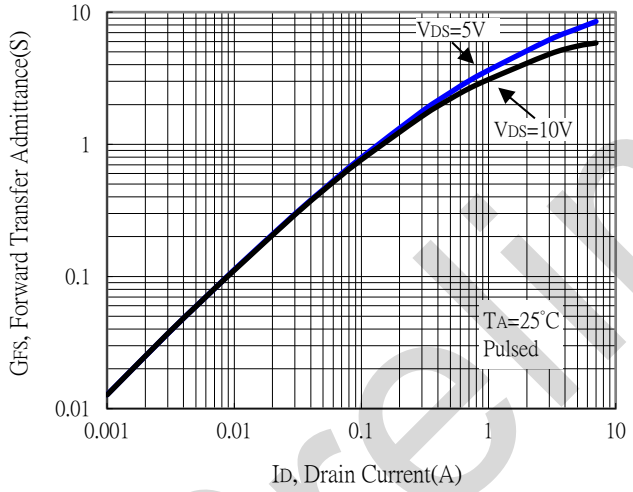
Capacitance vs Drain-to-Source Voltage



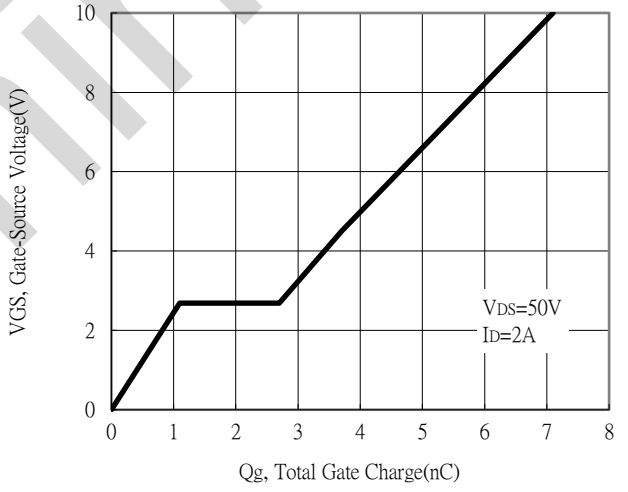
Threshold Voltage vs Junction Temperature



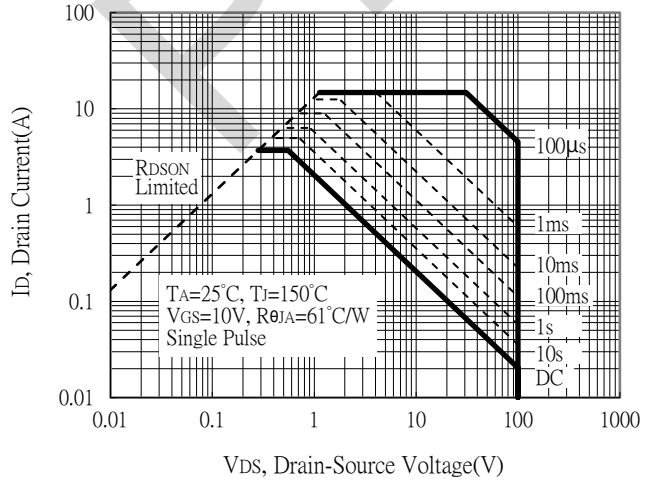
Forward Transfer Admittance vs Drain Current



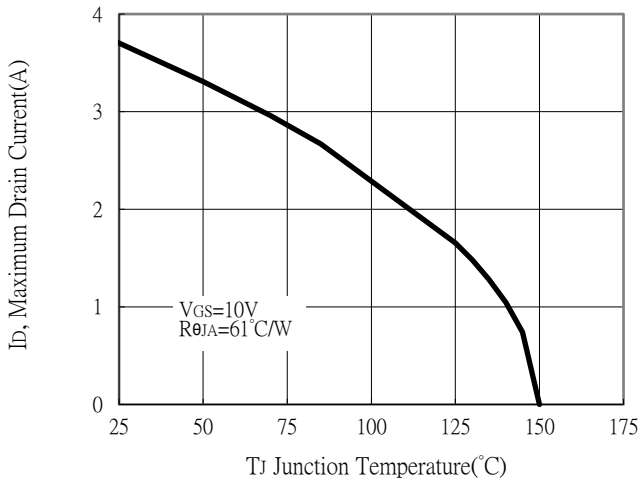
Gate Charge Characteristics



Maximum Safe Operating Area

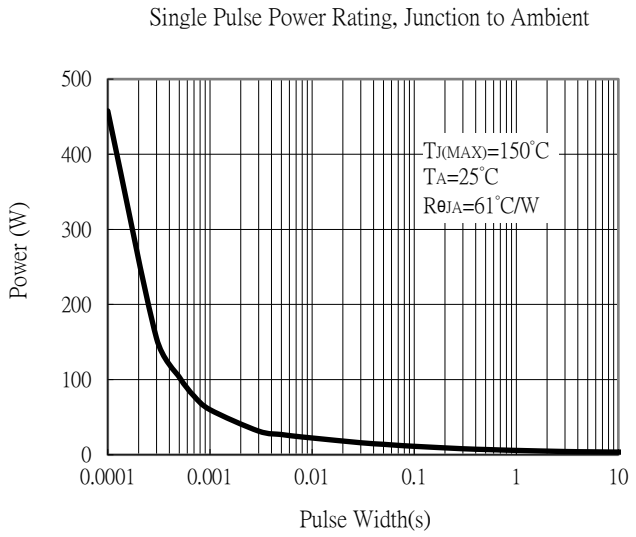


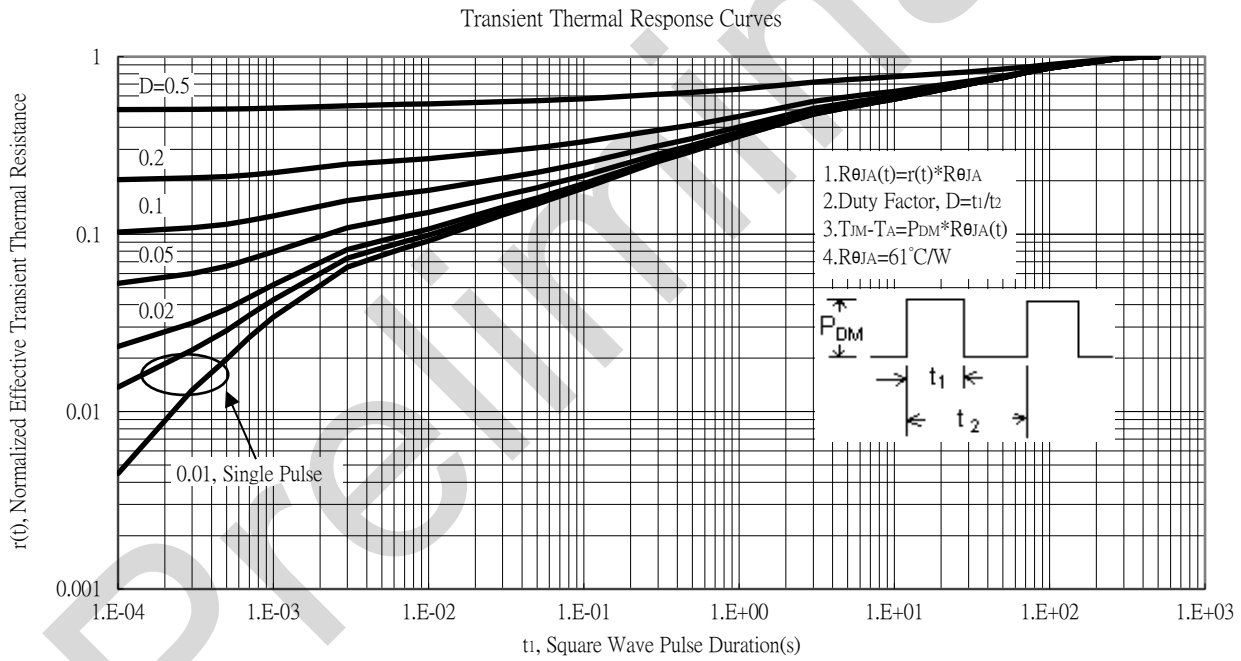
Maximum Drain Current vs Junction Temperature



Preliminary

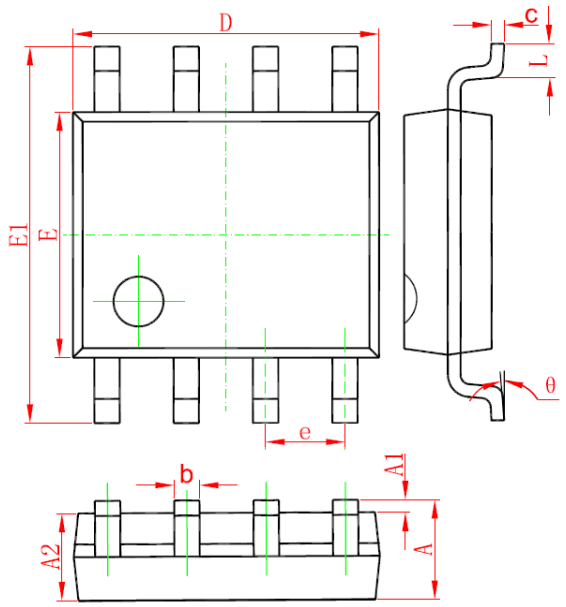
Typical Characteristics



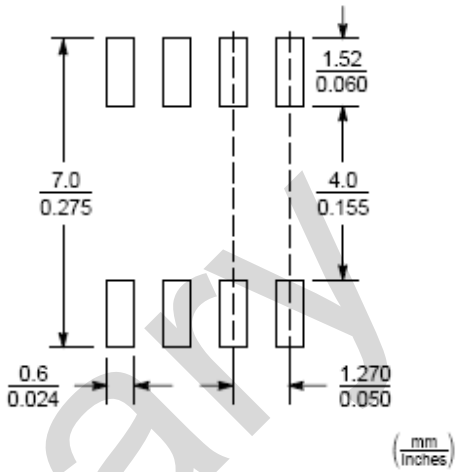


Preliminary

SOP-8 Dimension



8-Lead SOP-8 Plastic Package
CYS Package Code: Q8



Recommended Soldering Footprint

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Min.		Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069	E	3.800	4.000	0.150	0.157
A1	0.100	0.250	0.004	0.010	E1	5.800	6.200	0.228	0.244
A2	1.350	1.550	0.053	0.061	e	1.1270	TYP.	0.050	TYP.
b	0.330	0.510	0.013	0.020	L	0.400	1.270	0.016	0.050
c	0.170	0.250	0.006	0.010	θ	0°	8°	0°	8°
D	4.700	5.100	0.185	0.200					

Note:
- Controlling dimension: millimeters.
- Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:
- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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- CYStek assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

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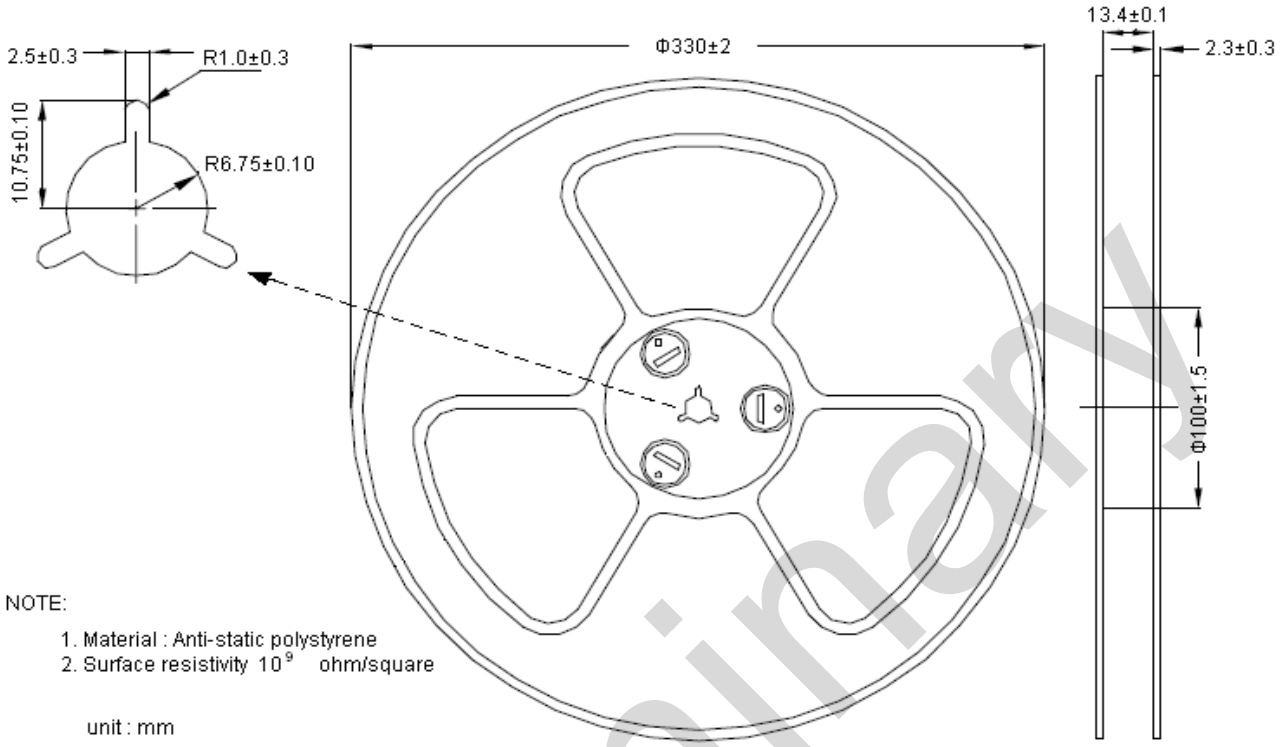
Reel Dimension

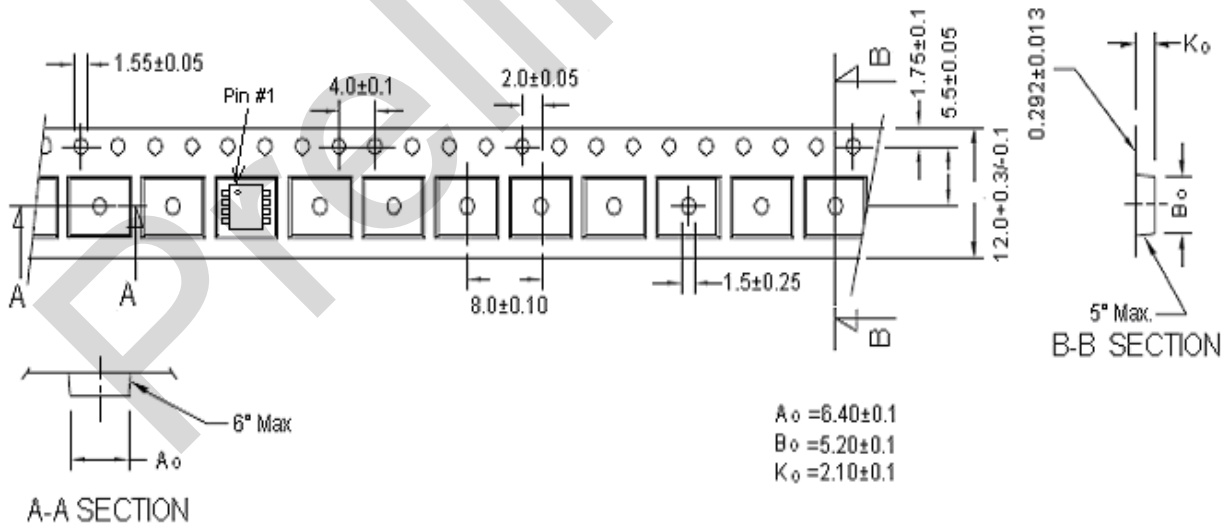


NOTE:

1. Material : Anti-static polystyrene
2. Surface resistivity 10^9 ohm/square

unit : mm

Carrier Tape Dimension



Notes:

1. 10 sprocket hole pitch cumulative tolerance ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material: conductive black polystyrene
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

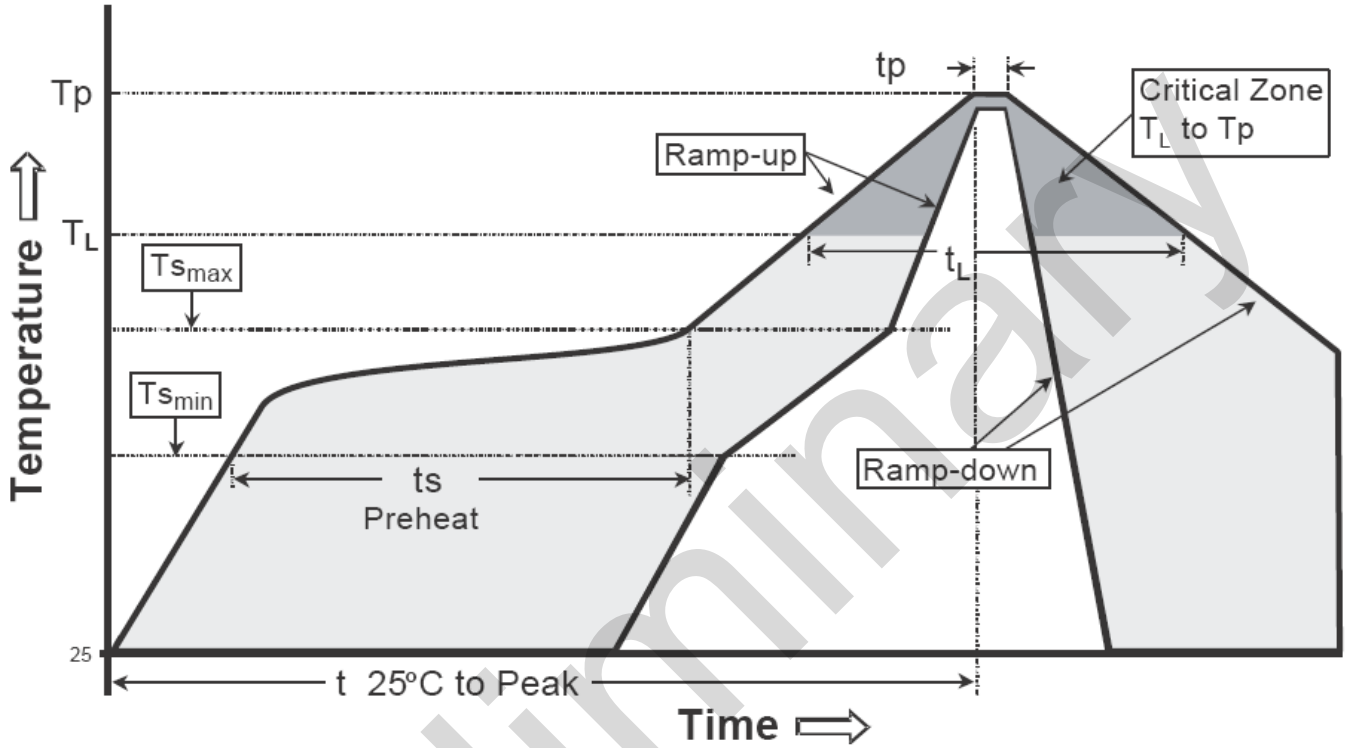
Uni : millimeter

Preliminary

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T_S max to T_P)	3°C/second max.	3°C/second max.
Preheat −Temperature Min (T_S min) −Temperature Max (T_S max) −Time (t_S min to t_S max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) −Time (t_L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature (T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature (t_P)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note:
- All temperatures refer to topside of the package, measured on
- For devices mounted on FR-4 PCB of 1.6mm or equivalent grade PCB. If other grade PCB is used, care should be taken to match the coefficients of thermal expansion between components and PCB. If they are not matched well, the solder joints may crack or the bodies of the parts may crack or shatter as the assembly cools.

Preliminary